

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
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EPAS ID: PAT5276214

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
JEE KWON PARK	12/10/2018
IK MO KIM	12/10/2018
NAM HYUN KIM	12/10/2018
JUNG KI KIM	12/10/2018
SANG HYUN HONG	12/10/2018
RECEIVING PARTY DATA	
Name:	LOTTE ADVANCED MATERIALS CO., LTD.
Street Address:	334-27, YEOSUSANDAN-RO
Internal Address:	YEOSU-SI, JEOLLANAM-DO
City:	YEOSU-SI
State/Country:	KOREA, REPUBLIC OF
Postal Code:	59616
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16215757
CORRESPONDENCE DATA	
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ATTORNEY DOCKET NUMBER:	1224.302
NAME OF SUBMITTER:	MELISSA B. PENDLETON
SIGNATURE:	/Melissa B. Pendleton/
DATE SIGNED:	12/11/2018

Total Attachments: 5

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RECORDATION FORM COVER SHEET PATENTS ONLY

To the Director of the U.S. Patent and Trademark Office: Please record the attached documents or the new address(es) below.

1. Name of conveying party(ies)
JEE KWON PARK
IK MO KIM
NAM HYUN KIM
JUNG KI KIM
SANG HYUN HONG
Additional name(s) of conveying party(ies) attached? Yes No

2. Name and address of receiving party(ies)
Name: Lotte Advanced Materials Co., Ltd.
Internal Address: _____

3. Nature of conveyance/Execution Date(s):
Execution Date(s) December 10, 2018
 Assignment Merger
 Security Agreement Change of Name
 Joint Research Agreement
 Government Interest Assignment
 Executive Order 9424, Confirmatory License
 Other _____

Street Address: 334-27, Yeosusandan-ro
_____ City: Yeosu-si
State: Jeollanam-do
Country: South Korea Zip: 59616
Additional name(s) & address(es) attached? Yes No

4. Application or patent number(s): This document is being filed together with a new application.
A. Patent Application No.(s)
16/215,757
Additional numbers attached? Yes No

B. Patent No.(s)

5. Name and address to whom correspondence concerning document should be mailed:
Name: Additon, Higgins & Pendleton, P.A.
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City: Charlotte
State: NC Zip: 28277-8202
Phone Number: 704-945-6700
Fax Number: 704-945-6735
Email Address: _____

6. Total number of applications and patents involved: 1
7. Total fee (37 CFR 1.21(h) & 3.41) \$ _____
 Authorized to be charged by credit card
 Authorized to be charged to deposit account
 Enclosed
 None required (government interest not affecting title)

8. Payment Information
a. Credit Card Last 4 Numbers _____
Expiration Date _____
b. Deposit Account Number _____
Authorized User Name _____

9. Signature: /Melissa B. Pendleton/ December 11, 2018
Signature Date
Melissa B. Pendleton
Name of Person Signing
Total number of pages including cover sheet, attachments, and documents: 5

Documents to be recorded (including cover sheet) should be faxed to (571) 273-0140, or mailed to:
Mail Stop Assignment Recordation Services, Director of the USPTO, P.O.Box 1450, Alexandria, V.A. 22313-1450

COMBINED DECLARATION AND ASSIGNMENT

WHEREAS, I, **Jee Kwon PARK**, a citizen of the Republic of Korea, with a mailing address of 56, Gosan-ro, Uiwang-si, Gyeonggi-do, Republic of Korea; **Ik Mo KIM**, a citizen of the Republic of Korea, with a mailing address of 56, Gosan-ro, Uiwang-si, Gyeonggi-do, Republic of Korea; **Nam Hyun KIM**, a citizen of the Republic of Korea, with a mailing address of 56, Gosan-ro, Uiwang-si, Gyeonggi-do, Republic of Korea; **Jung Ki KIM**, a citizen of the Republic of Korea, with a mailing address of 56, Gosan-ro, Uiwang-si, Gyeonggi-do, Republic of Korea; and **Sang Hyun HONG**, a citizen of the Republic of Korea, with a mailing address of 56, Gosan-ro, Uiwang-si, Gyeonggi-do, Republic of Korea (hereinafter referred to as "ASSIGNOR"), am a joint inventor of certain new and useful improvements (hereinafter collectively referred to as "INVENTION") in *Thermoplastic Resin Composition for Laser Direct Structuring Process and Article Comprising the Same*, for which an application for United States Letters Patent is being filed concurrently herewith and which application claims priority from a Korean application filed on December 12, 2017, under Serial No. 10-2017-0170368, and a Korean application filed on October 1, 2018, under Serial No. 10-2018-0117233, all applications listed above being hereinafter referred to as the "APPLICATION"; and

WHEREAS, Lotte Advanced Materials Co., Ltd., a corporation of the Republic of Korea (hereinafter referred to as "ASSIGNEE"), having a principal place of business at 334-27, Yeosusandan-ro, Yeosu-si, Jeollanam-do, 59616, Republic of Korea, has acquired the equitable right, title, and interest—and is desirous of acquiring any remaining right, title, and interest—in and to

said INVENTION as described in said APPLICATION, and in and to any and all Letters Patent that shall be granted with respect to said INVENTION in the United States of America and all foreign countries;

NOW, THEREFORE, be it known that for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, I, the ASSIGNOR, have sold, assigned, transferred, and conveyed unto said ASSIGNEE, its successors and assigns, my equitable right, title, and interest—and by these presents do hereby sell, assign, transfer, and convey unto said ASSIGNEE, its successors and assigns any remaining right, title, and interest—in and to said INVENTION and APPLICATION, in and to any and all continuations, continuations-in-part, or divisions thereof, and in and to any and all Letters Patent of the United States of America and all foreign countries or reissues, reexaminations, or extensions thereof that may be granted therefore or thereon, for the full term for which said Letters Patent may be granted, together with the right to claim the priority of said APPLICATION in all foreign countries in accordance with international treaties and conventions, the same to be held and enjoyed by said ASSIGNEE, its successors and assigns, as fully and entirely as the same would have been held and enjoyed by me if an assignment and sale had not been made.

I acknowledge that at the time the INVENTION was made, the INVENTION was subject to an obligation of assignment to said ASSIGNEE. I further acknowledge that said ASSIGNEE has the sole right to determine patent prosecution strategies with respect to said INVENTION and all corresponding applications, and hereby request that Letters Patent be issued in accordance with this assignment.

I further covenant and agree to bind my heirs, legal representatives, and assigns, promptly to communicate to said ASSIGNEE or its representatives any facts known to me relating to said INVENTION, to testify in any interference or legal proceedings involving said INVENTION, to execute any additional papers that may be requested to confirm the right of the ASSIGNEE, its representatives, successors or assigns to secure patent or similar protection for said INVENTION in all countries and to vest in the ASSIGNEE complete title to said INVENTION and Letters Patent, without further compensation, but at the expense of said ASSIGNEE, its successors, assigns and other legal representatives.

As the below named inventor, I hereby declare:

The application for United States Letters Patent being filed concurrently herewith was made or authorized to be made by me.

I believe that I am the original or an original joint inventor of a claimed invention in the application.

I hereby acknowledge that any willful false statement made in the declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

IN WITNESS WHEREOF, I have hereunto signed my name on the day and year set forth below.

December 10, 2018

박기권
Jee Kwon PARK

12, 10, 2018

김익모
Ik Mo KIM

Dec 10, 2018

김남현
Nam Hyun KIM

12, 10, 2018

Jung Ki KIM

Jung Ki KIM

Dec 10

, 2018

홍성현

Sang Hyun HONG